FQA44N30

300V N-Channel MOSFET

General Description

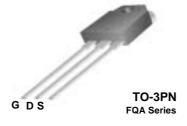
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

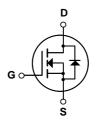
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply.

Features

- 43.5A, 300V, R_{DS(on)} = 0.069Ω @V_{GS} = 10 V
 Low gate charge (typical 120 nC)
 Low Crss (typical 75 pF)

- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQA44N30	Units	
V _{DSS}	Drain-Source Voltage		300	V	
I _D	Drain Current - Continuous (T _C = 25°	(C)	43.5	A	
	- Continuous (T _C = 100)°C)	27.5	A	
I _{DM}	Drain Current - Pulsed	(Note 1)	174	А	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	1700	mJ	
I _{AR}	Avalanche Current	(Note 1)	43.5	А	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	31	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P_D	Power Dissipation (T _C = 25°C)		310	W	
	- Derate above 25°C		2.5	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.4	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	300			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.32		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 300 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 240 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 21.75 A		0.055	0.069	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 21.75 A (Note 4)		30		S
C _{oss}	Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		810 75	1050 95	pF pF
C _{rss}	Reverse Transfer Capacitance			75	95	pF
Switch	ing Characteristics					
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 150 \text{ V}, I_{D} = 43.5 \text{ A},$ $R_{G} = 25 \Omega$		85	180	ns
t _r	Turn-On Rise Time			470	950	ns
$t_{d(off)}$	Turn-Off Delay Time			240	490	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		230	470	ns
Qg	Total Gate Charge	V _{DS} = 240 V, I _D = 43.5 A,		120	150	nC
9						
	Gate-Source Charge	V _{GS} = 10 V		29		nC
Q _{gs}	Gate-Source Charge Gate-Drain Charge	V _{GS} = 10 V (Note 4, 5)		29 58		nC nC
Q _{gs} Q _{gd}	Gate-Drain Charge	(Note 4, 5)				
Q _{gs} Q _{gd}		(Note 4, 5)				
Q _{gs} Q _{gd} Drain-S	Gate-Drain Charge	(Note 4, 5) nd Maximum Ratings ode Forward Current		58		nC
Q _{gs} Q _{gd} Drain-S I _S I _{SM}	Gate-Drain Charge Source Diode Characteristics as Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	(Note 4, 5) nd Maximum Ratings ode Forward Current Forward Current		58	43.5	nC A
Q _{gs} Q _{gd} Drain-S	Gate-Drain Charge Source Diode Characteristics at Maximum Continuous Drain-Source Dio	(Note 4, 5) nd Maximum Ratings ode Forward Current		 	43.5 174	nC A A

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 1.5mH, I_{AS} = 43.5A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} \leq 43.5A, di/dt \leq 200A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

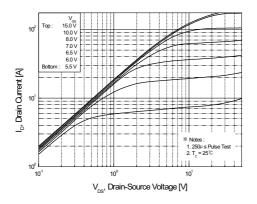


Figure 1. On-Region Characteristics

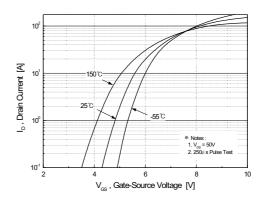


Figure 2. Transfer Characteristics

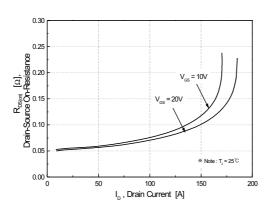


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

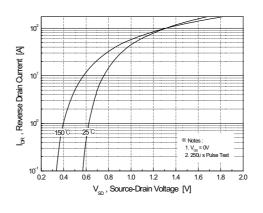


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

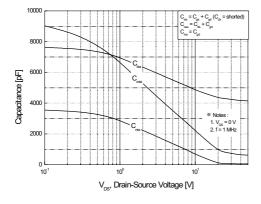


Figure 5. Capacitance Characteristics

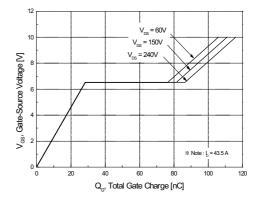


Figure 6. Gate Charge Characteristics

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Typical Characteristics (Continued)

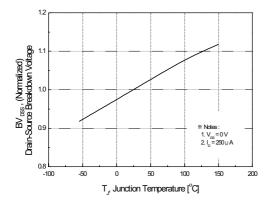
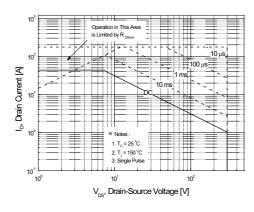


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



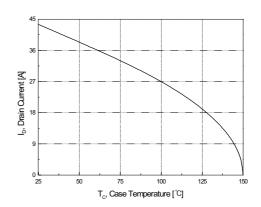


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

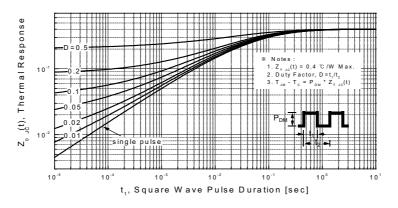
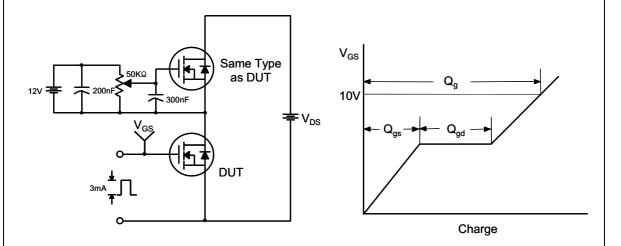


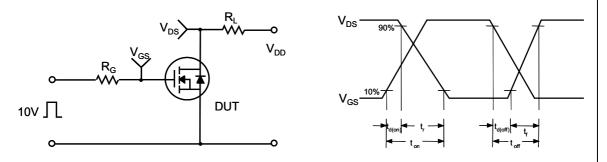
Figure 11. Transient Thermal Response Curve

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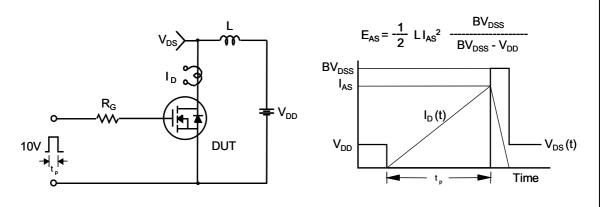
Gate Charge Test Circuit & Waveform



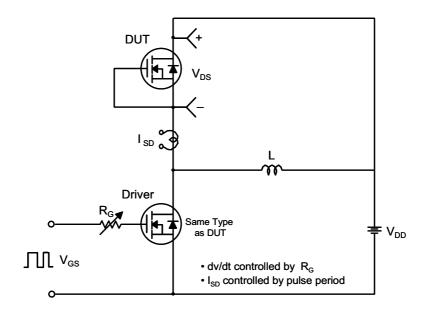
Resistive Switching Test Circuit & Waveforms

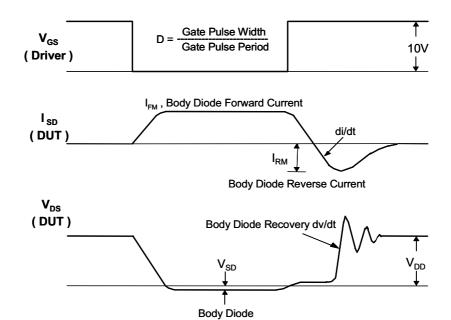


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

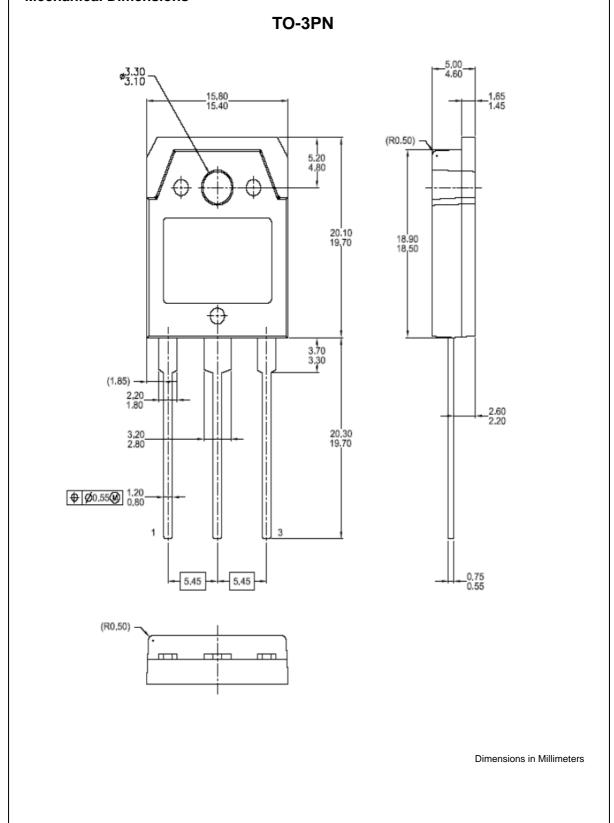




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Forward Voltage Drop

Mechanical Dimensions



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